

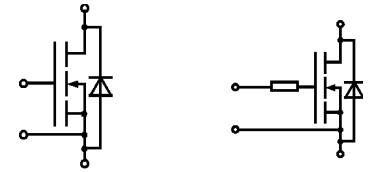
| Absolute Maximum Ratings | | Values | Units |
|--------------------------|------------------------------|--------------------|-------|
| Symbol | Conditions ¹⁾ | | |
| V_{DS} | | 800 | V |
| V_{DGR} | $R_{GE} = 20\text{ k}\Omega$ | 800 | V |
| I_D | | 36 | A |
| I_{DM} | | 144 | A |
| V_{GS} | | ± 20 | V |
| P_D | | 700 | W |
| $T_j, (T_{stg})$ | | -40 ... +150 (125) | °C |
| V_{isol} | AC, 1 min. | 2 500 | V |
| humidity | DIN 40 040 | Class F | |
| climate | DIN IEC 68 T.1 | 40/125/56 | |
| Inverse Diode | | | |
| $I_F = -I_D$ | | 36 | A |
| $I_{FM} = -I_{DM}$ | | 144 | A |

SEMITRANS® M Power MOSFET Modules

SKM 181 A3 ³⁾
SKM 181 A3R *)



SEMITRANS M1



SKM 181 A3 SKM 181 A3R *)

Features

- N Channel, enhancement mode
- Short internal connections avoid oscillations
- DCB-ceramic isolated copper baseplate
- All electrical connections on top for easy busbaring
- Large clearance (10 mm) and creepage distances (13 mm)
- UL recognized, file no. E63 532

Typical Applications

- Switched mode power supplies
- DC servo and robot drives
- DC choppers
- Resonant and welding inverters
- AC motor drives
- Laser power supplies
- UPS equipment
- Plasma cutting
- Not suitable for linear amplification

*) SKM 181 A3R has built-in gate resistor chips ("R") $R_{ginternal} = 1,3\Omega$, preferred typed for paralleling and for lower switching frequencies

This is an electrostatic discharge sensitive device (ESDS). Please observe the international standard IEC 747-1, Chapter IX.

| Characteristics | | min. | typ. | max. | Units |
|-----------------------------|--|------|------|------|---------------|
| Symbol | Conditions ¹⁾ | | | | |
| $V_{(BR)DSS}$ | $V_{GS} = 0, I_D = 0,25\text{ mA}$ | 800 | – | – | V |
| $V_{GS(th)}$ | $V_{GS} = V_{DS}, I_D = 1\text{ mA}$ | 2,1 | 3,0 | 4,0 | V |
| I_{DSS} | $V_{GS} = 0$ } $T_j = 25\text{ °C}$ $V_{DS} = 800\text{ V}$ } $T_j = 125\text{ °C}$ | – | 50 | 100 | μA |
| | | – | 300 | 1000 | μA |
| I_{GSS} | $V_{GS} = 20\text{ V}, V_{DS} = 0$ | – | 10 | 100 | nA |
| $R_{DS(on)}$ | $V_{GS} = 10\text{ V}, I_D = 23\text{ A}$ | – | 170 | 210 | m Ω |
| g_{fs} | $V_{DS} = 10\text{ V}, I_D = 23\text{ A}$ | 16 | 33 | – | S |
| C_{CHC} | $V_{GS} = 0$ $V_{DS} = 25\text{ V}$ $f = 1\text{ MHz}$ | – | – | 160 | pF |
| C_{iss} | | – | 10 | 14 | nF |
| C_{oss} | | – | 1,2 | 1,7 | nF |
| C_{rss} | | – | 0,6 | 0,8 | nF |
| L_{DS} | | – | – | 20 | nH |
| $t_{d(on)}$ | $V_{DD} = 400\text{ V}$ $I_D = 23\text{ A}$ | – | 60 | – | ns |
| t_r | | – | 30 | – | ns |
| $t_{d(off)}$ | $V_{GS} = 10\text{ V}$ $R_G = 4,7\text{ }\Omega$ (SKM 181A3R: 3,3 Ω) | – | 350 | – | ns |
| t_f | | – | 70 | – | ns |
| Inverse Diode ⁸⁾ | | | | | |
| V_{SD} | $I_F = 72\text{ A}, V_{GS} = 0\text{ V}$ | – | 0,9 | 1,2 | V |
| t_{rr} | $T_j = 25\text{ °C}^2)$ | – | 1200 | – | ns |
| | $T_j = 150\text{ °C}^2)$ | – | – | – | ns |
| Q_{rr} | $T_j = 25\text{ °C}^2)$ | – | 42 | – | μC |
| | $T_j = 150\text{ °C}^2)$ | – | – | – | μC |
| Thermal characteristics | | | | | |
| R_{thjc} | | – | – | 0,18 | °C/W |
| R_{thch} | M_1 , surface 10 μm | – | – | 0,05 | °C/W |

| Mechanical Data | | | | | |
|-----------------|-------------------------|-----|---|--------|------------------|
| M_1 | to heatsink, SI Units | 4 | – | 5 | Nm |
| | to heatsink, US Units | 35 | – | 44 | lb.in. |
| M_2 | for terminals, SI Units | 2,5 | – | 3,5 | Nm |
| | for terminals, US Units | 22 | – | 24 | lb.in. |
| a | | – | – | 5x9,81 | m/s ² |
| w | | – | – | 130 | g |
| Case | → B 5 – 25 | | | D15 | |

¹⁾ $T_{case} = 25\text{ °C}$, unless otherwise specified

²⁾ $I_F = -I_D, V_R = 100\text{ V}, -di_f/dt = 100\text{ A}/\mu\text{s}$

³⁾ SKM 181 A 3 (with standard recovery body drain diode) can replace old SKM 181 F (with fast recovery body drain diode) only in DC-choppers and resonant inverters which do not use the fast recovery feature i. e. $f_{sw} > f_{resonant}$, but not for $f_{sw} < f_r$ and not for PWM-inverters. In doubt please ask SEMİKRON.

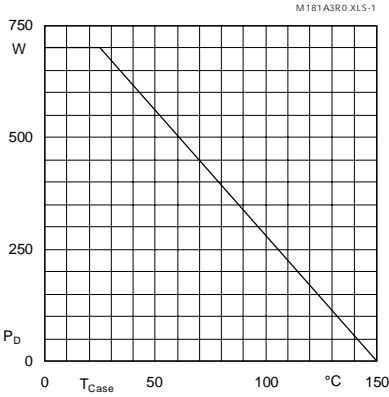


Fig. 1 Rated power dissipation vs. temperature

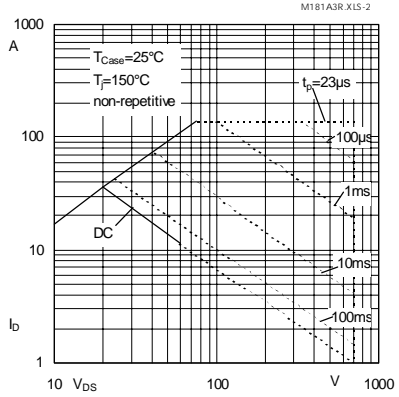


Fig. 2 Maximum safe operating area

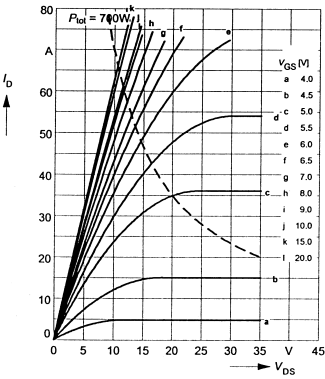


Fig. 3 Output characteristic

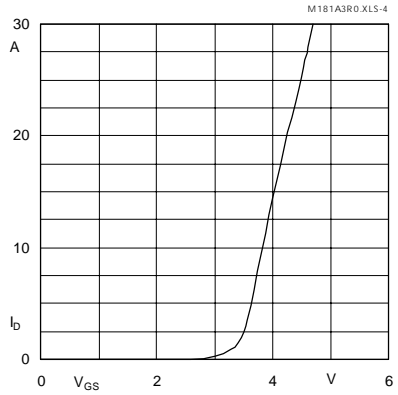


Fig. 4 Transfer characteristic

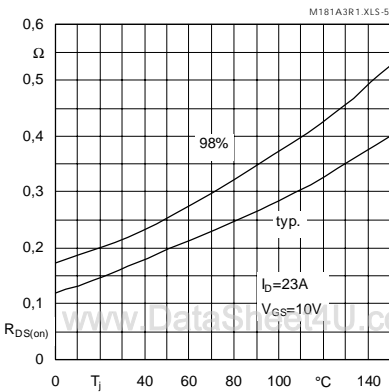


Fig. 5 On-resistance vs. temperature

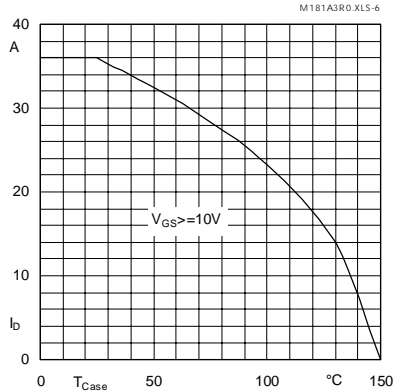


Fig. 6 Rated current vs. temperature

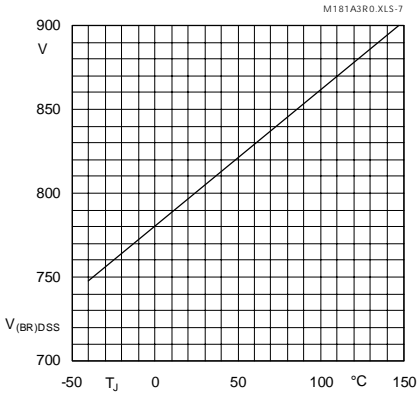


Fig. 7 Breakdown voltage vs. temperature

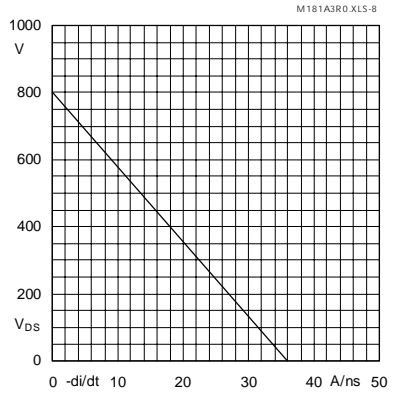


Fig. 8 Drain-source voltage derating

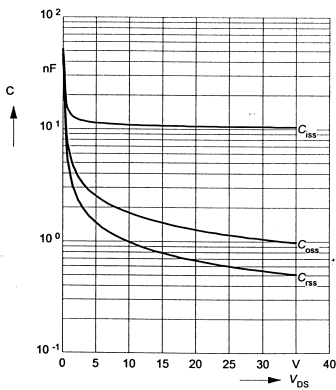


Fig. 9 Typ. capacitances vs. drain-source voltage

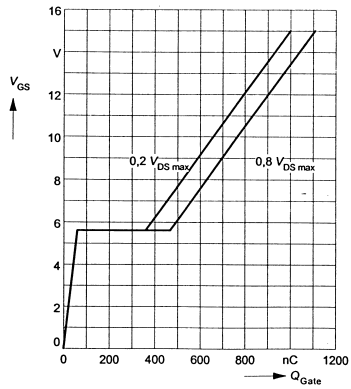


Fig. 10 Gate charge characteristic

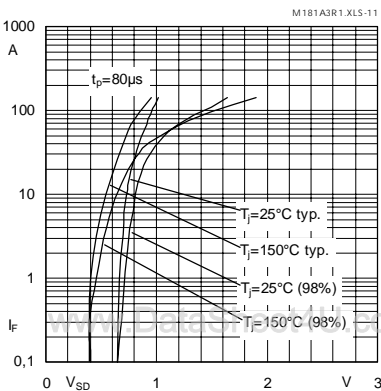


Fig. 11 Diode forward characteristic

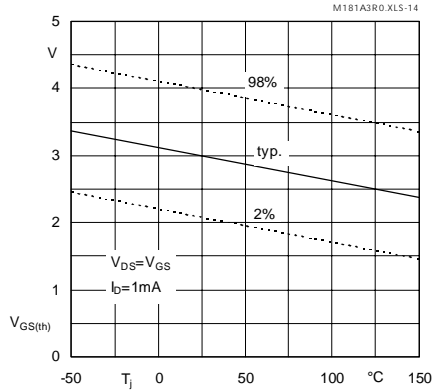


Fig. 14 Gate-source threshold voltage

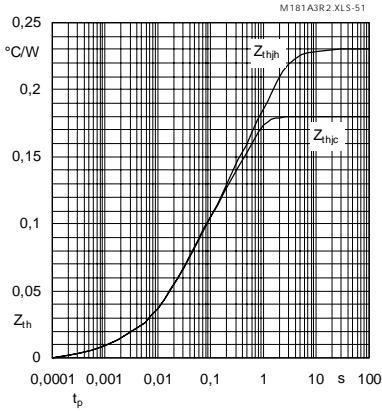


Fig. 51 Transient thermal impedance

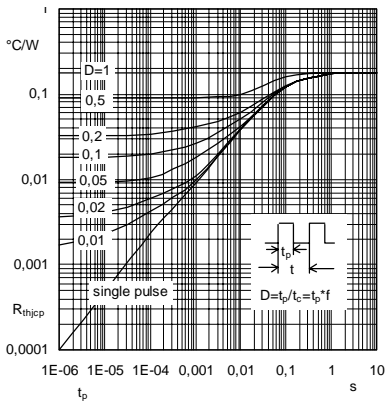


Fig. 52 Thermal impedance under pulse conditions

